



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Kenneth A. Bandy, et al.

Examiner: Lan Vinh

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Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated February 17, 2005, applicants submit the following amendments and remarks for entry of record in the above-identified patent application.

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: June 17, 2005



Leslie S. Szivos, Ph.D